TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XCM526xxxxDR-G
Typical Mass: 9 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.167	Silicon	129700	7440-21-3
	0.033	Gold	3700	7440-57-5
Lead pad	2.248	Nickel	249800	7440-02-0
	0.178	Silver	19800	7440-22-4
	0.033	Gold	3600	7440-57-5
Die attach	0.040	Silver	4500	7440-22-4
	0.007	Epoxy Resin	700	—
Bonding wire	0.170	Gold	18900	7440-57-5
Resin	4.611	Silica	512300	60676-86-0
	0.282	Epoxy Resin	31300	—
	0.231	Phenol Resin	25600	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."